Polymer 103 (2016) 140-145

Contents lists available at ScienceDirect

### Polymer

journal homepage: www.elsevier.com/locate/polymer



# Syntheses and polymerization of epoxy monomers consisting of carbosilane segments and properties of the networked polymers

Ayumu Karimata <sup>a</sup>, Kozo Matsumoto <sup>a, b</sup>, Takeshi Endo <sup>a, \*</sup>

<sup>a</sup> Molecular Engineering Institute, Kindai University, 11-6 Kayanomori, lizuka, Fukuoka, 820-8555, Japan <sup>b</sup> Department of Biological & Environmental Chemistry, Kindai University, 11-6 Kayanomori, lizuka, Fukuoka, 820-8555, Japan

#### ARTICLE INFO

Article history: Received 5 July 2016 Received in revised form 8 September 2016 Accepted 15 September 2016 Available online 15 September 2016

*Keywords:* Carbosilane Silicon Epoxy resin

#### ABSTRACT

Two diglycidyl ethers which consist of a flexible carbosilane segments and of rigid phenylene moieties (**1** and **2**) were synthesized and investigated in order to evaluate their heat-curing behavior (epoxy homopolymerization) as well as thermal and mechanical properties of the networked polymers. Differential scanning calorimetry (DSC) analysis revealed that melting points of both diepoxides were -73.9 and -50.7 °C, respectively. Networked polymers of **1** and **2** showed glass transition temperature ( $T_g$ )s below ambient temperature of 2.2 and 18.7 °C, respectively. High thermal stability of cured **1** and **2** were confirmed by thermogravimetric analysis (TGA) (5% weight loss temperature ( $T_{d5}$ ) = 369 °C for **1** and 351 °C for **2**). Tensile tests of cured **1** and **2** clarified that their Young's moduli were (9.76 ± 0.135)<sup>-2</sup> and (1.29 ± 0.114)<sup>-1</sup> MPa, respectively.

© 2016 Elsevier Ltd. All rights reserved.

### 1. Introduction

Epoxy resins are one of the most important thermoset materials in the industrial applications such as coatings, adhesives, electrical insulations, and composites [1–5]. Epoxy resins require high chemical and thermal stabilities, high durability, good adhesion and mechanical properties as well as good reactivities. In addition, fine-tuning of these properties are of the necessary for particular applications. To control the characteristics of epoxy resins, introducing a heteroatom component is considered great effective. Thus, we focused on introducing carbosilane as a component for epoxy resins. Polycarbosilanes, consisting of whole backbone C-Si-C, generally show high thermal stabilities with low glass transition temperature  $(T_g)$  [6–11]. Although polysiloxanes exhibit low  $T_g$ , the chemical stability of carbosilanes are higher than those of siloxanes in general. Because Si-C bond is less polarized than Si-O bond, Si-C bonds are less prone to be hydrolysed or attacked by nucleophiles [17]. A great number of researches on development of siloxane-based epoxy resins have been reported [12], while studies about carbosilane-based epoxy resins have been limited so far. Poly [1,1-diethylsilabutane-co-1-(3,4-epoxybutyl)-1-methylsilabutane] has been reported from our laboratory. It can be cationically cured

\* Corresponding author. E-mail address: tendo@moleng.fuk.kindai.ac.jp (T. Endo). to provide networked polymers with good thermal stability ( $T_{d5}$  of >380 °C) [13], which suggested a large potential of carbosilanebased network polymers.

In this study, we synthesized carbosilane-based epoxy monomers **1** and **2**, which consist of not only flexible C–Si–C bonds and alkyl chains but also rigid phenylene units, and compared their reactivity for cationic polymerization and the properties of their cured resins with the representative epoxy monomer bisphenol A diglycidyl ether (**BADGE**). We expected that the epoxy resins bearing a carbosilane segment would show lower  $T_g$  and Young's moduli as well as high thermal properties, which will be a useful information in the development of new epoxy resins for the elastomer applications.

### 2. Experimental

### 2.1. Analyses and measurements

<sup>1</sup>H (400 MHz) and <sup>13</sup>C (100 MHz) NMR spectra were recorded on JEOL JME-ECS 400 NMR spectrometer in CDCl<sub>3</sub>. Chemical shifts were determined relative to internal TMS (<sup>1</sup>H, δ 0.00) or internal CDCl<sub>3</sub> (<sup>13</sup>C, δ 77.16). Attenuated total reflection fourier transform infrared spectroscopy (ATR-FTIR) analyses were recorded by using a Thermo Scientific Nicolet iS10 spectrometer equipped with a Smart iTR diamond ATR sampling accessory. Differential scanning calorimetry (DSC) analyses were carried out using Seiko Instrument





polyme

DSC-6200R in an aluminum pan under a nitrogen flow of 50 mL min<sup>-1</sup>. Thermogravimetric analysis (TGA) were performed on a Seiko Instrument TG-DTA 6200 using an aluminum pan under nitrogen atmosphere (flow rate 100 mL min<sup>-1</sup>) at a heating rate of 10 °C min<sup>-1</sup>. Tensile testing was conducted and recorded on tensile testing machine (EZ-LX, SHIMADZU) using dumbbell-shaped films (ca. 0.3 mm (T)  $\times$  2 mm (W)  $\times$  12 mm (L)) with speed of 500 mm/ min. Reported values of Ultimate strength, Strain at break and Young's modulus (*E*) are average and standard deviations of three samples.

### 2.2. Materials

1,4-bis(dimethylsilyl)benzene and platinum(0)-1,3-divinyl-1,1,3,3-tetramethyl disiloxane complex in xylene [2 wt%] were purchased form Aldrich. Bisphenol A diglycidyl ether (**BADGE**, 99% purity) was purchased from ADEKA corporation. Methanol and chloroform were purchased from Wako Pure Chemical Industry (Osaka, Japan). 2-methylbenzylmethyl-*p*-hydroxyphenylsulfonium hexafluoroantimonate (SAN-AID SI-80) was purchased from Sanshin Chemical Industry co., ltd. 4-vinylbenzyl glycidylehter was purchased from AGC Seimi Chemical (Kanagawa, Japan). All the reagents were used without further purification. Silica gel 60 (70–230 mesh ASTM) for column chromatography was purchased from Merck (Japan).

### 2.2.1. Synthesis of 1,4-bis(dimethyl(3-(oxiran-2-ylmethoxy)propyl) silyl)benzene (1)

Platinum(0)-1,3-divinyl-1,1,3,3-tetramethyl disiloxane complex in xylene [2 wt%] (0.02 mL, 0.9 µmol) was added to a mixture of 1,4bis(dimethylsilyl)benzene (975 mg, 5.01 mmol) and allyl glycidyl ehter (1.19 g, 10.4 mmol) at 0 °C under a N<sub>2</sub> atmosphere. After stirring for 10 min, the reaction mixture was allowed to warm to room temperature and stirred for 1 h. The reaction mixture was purified by silica column chropatography using hexane-ether (2:1) as an eluent to give a colorless oil (2.05 g, 97%). <sup>1</sup>H NMR (400 MHz, CDCl<sub>3</sub>,  $\delta$ , ppm): 7.48 (s, 4H), 3.68 (dd, I = 8.7 and 2.4 Hz, 2 H), 3.42 (m, 4H), 3.36, (m, 2H), 3.13 (m, 2H), 2.79, (t, *J* = 3.9 Hz, 2H), 2.60 (m, 2H), 1.62 (m, 4H), 0.74 (m, 4H), 0.27 (s, 12H). <sup>13</sup>C NMR (100 MHz, CDCl<sub>3</sub>, *b*, ppm): 139.88, 133.00, 74.47, 71.59, 51.00, 4452, 24.23, 11.76, -3.07. <sup>29</sup>Si NMR (400 MHz, CDCl<sub>3</sub>, δ, ppm): 2.73. ATR-FTIR (v, cm<sup>-1</sup>): 2930, 2866, 1380, 1337, 1248, 1133, 1105, 1057, 909, 833, 797, 764, 735. HRMS [FAB] *m*/*z* Calcd. for C<sub>22</sub>H<sub>38</sub>O<sub>4</sub>Si<sub>2</sub>: 422.2309, Found  $[M + H^+]$  423.2384.

### 2.2.2. Synthesis of 1,4-bis(dimethyl(4-((oxiran-2-ylmethoxy) methyl)phenethyl)silyl)benzene (**2**)

Platinum(0)-1,3-divinyl-1,1,3,3-tetramethyl disiloxane complex in xylene [2 wt%] (0.02 mL, 0.9 µmol) was added to a mixture of 1,4bis(dimethylsilyl)benzene (978 mg, 5.03 mmol) and 4-vinylbenzyl glycidylehter (1.90 g, 9.99 mmol) at 0 °C under a N<sub>2</sub> atmosphere. After stirring for 10 min, the reaction mixture was allowed to warm to room temperature and stirred for 3 h. The reaction mixture was purified by silica column chropatography using hexane-ether (2:1) as an eluent to give a colorless oil (2.57 g, 90%). <sup>1</sup>H NMR (400 MHz, CDCl<sub>3</sub>,  $\delta$ , ppm): 7.53 (s, 4H), 7.24 (d, J = 6.3 Hz, 4 H), 7.16 (d, J = 6.3 Hz, 4 H), 4.54 (quart., J = 8.4 Hz, 4 H), 3.73 (dd, J = 8.7 and 2.4 Hz, 2 H), 3.41 (m, 2H), 3.18 (m, 2H), 2.79 (t, J = 3.9 Hz, 2H), 2.66–2.61 (m, 6H) 1.11, (m, 4H), 0.29 (s, 12H). <sup>13</sup>C NMR (100 MHz, CDCl<sub>3</sub>, *δ*, ppm): 144.80, 139.84, 133.05, 128.08, 127.96, 73.33, 70.75, 51.02, 44.47, 29.79, 17.76, -3.02. <sup>29</sup>Si NMR (400 MHz, CDCl<sub>3</sub>, δ, ppm): 3.02. ATR-FTIR (v, cm<sup>-1</sup>): 2951, 1513, 1417, 1380, 1248, 1133, 1090, 1019, 902, 834, 811, 767, 691. HRMS [FAB] m/z Calcd. for C<sub>34</sub>H<sub>46</sub>O<sub>4</sub>Si<sub>2</sub>: 574.2935, Found: [M<sup>+</sup>]574.2925.

### 2.3. Preparation of cured resins of 1 and 2

Monomer **1** or **2** (4 mmol) and 2-methylbenzylmethyl-*p*-hydroxyphenylsulfonium hexafluoroantimonate (SAN-AID SI-80) (0.2 mmol) were dissolved in a solution of chloroform—methanol (8:1/v:v). The solution was casted into Petri dish made from polytetrafluoroethylene and the solvents were evaporated at room temperature for 15 h. The sample was further dried under vacuum at room temperature for 24 h. The sample was heated at 100 °C for 2 h, then 130 °C for 1 h under a N<sub>2</sub> atmosphere.

### 3. Results and discussion

#### 3.1. Syntheses of epoxy monomers 1 and 2

Syntheses of carbosilane-containing diepoxy monomers **1** and **2** were outlined in Scheme 1. Hydrosylilation of allylglycidylether or 4-vinylbenzylglycidylether with 1,4-bis(dimethylsilyl)benzene were carried out using Karsted's catalyst to obtain diepoxy monomers **1** and **2** in 97 and 90% yields, respectively. Compound **1** has been already reported [14], but curing properties of monomer **1** has not been studied. Nuclear magnetic resonance (NMR) spectroscopy confirmed the chemical structures of **1** and **2**. <sup>1</sup>H NMR spectra of **1** and **2** in CDCl<sub>3</sub> are shown in Fig. 1. A 12H singlet signal corresponding to Si–CH<sub>3</sub> protons (b) was observed in upfield region (0.265 ppm for **1** and 0.290 ppm for **2**). Ten protons on diglycidyl ether moieties (f, g, h, i, j for **1** and h, i, j, k, l for **2**) around 2.5–4 ppm and 4H singlet signals on bis(dimethylsilyl)phenylene at 7.48 ppm for **1** and 7.53 ppm for **2** were also observed, which confirmed the corresponding chemical structures of **1** and **2**.

### 3.2. Curing behavior of 1 and 2

Differential scanning calorimetry (DSC) scans of monomers **1** and **2** are shown in Fig. 2a. The melting points of **1** and **2** are determined to be -73.9 and -50.3 °C from the peak top of heating cycle of DSC scans. These low melting points might be due to the C–Si–C bonds and flexible alkyl chains.

To gain insight into the thermal cationic polymerization, DSC analyses of 1 and 2 were performed with mixing 5 mol% of the thermally-latent cationic initiator: 2-methylbenzylmethyl-phydroxyphenylsulfonium hexafluoroantimonate (The chemical structure is shown in supporting information). DSC analysis of BADGE was also performed under the same condition as reference experiment. With the addition of the thermally-latent initiator, DSC curve (heating scan) of 1 showed exothermic peak around 70-160 °C, which can be attributed to the exotherm by ringopening polymerization of the epoxy moieties (Fig. 2b). Similar tendencies were also observed for 2 and BADGE (see supporting information). Further experimental information about the cationic ring-opening reactions of these glycidyl ethers 1 and 2 were obtained by DSC analyses conducted at different heating rate. The samples containing 5 mol% of 2-methylbenzylmethyl-p-hydroxyphenylsulfonium hexafluoroantimonate were scanned at heating rates of 5, 10, 15, and 20 °C/min. The DSC curves of 1 and 2 are shown in Fig. 3a and b along with the peak top temperature  $(T_p)$ . As increasing the heating rate, the  $T_{ps}$  were shifted to higher temperature. From these results, activation energies  $(E_{\alpha})$ s of **1**, **2** and BADGE were estimated using both Ozawa's method (eq (1)) and Kissinger's method (eq (2)) [15,16], as follows:

$$\ln q = -1.052 \times E_a / RT_p + \ln(AE_a/R) - \ln F_{(x)} - 5.331$$
(1)

Download English Version:

## https://daneshyari.com/en/article/5178676

Download Persian Version:

https://daneshyari.com/article/5178676

Daneshyari.com